

Docket No.: TESSERA 3.0-051 FWC DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Joseph Fjelstad

Application No.: 09/707,452

: Group Art Unit: 2841

Filed: November 7, 2000

: Examiner: R. Chang

For: CONNECTION COMPONENTS WITH POSTS

Commissioner for Patents
Washington, DC 20231

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TECHNOLOGY CENTER R3700

AMENDMENT

Dear Sir:

In response to the official action mailed September 25, 2002, applicant submits the following amendments and remarks.

IN THE TITLE

Amend the Title to read: --Forming Conductive Posts of
By Selective Removal of Conductive Material.--

IN THE ABSTRACT

Please delete the Abstract as filed and substitute therefor the attached revised Abstract.

~~IN THE CLAIMS~~

1. (Twice Amended) A method of fabricating interconnection members for a microelectronic device, the method comprising:

providing a support substrate having a first surface;
coupling a conductive sheet having a uniform thickness
to the first surface of the support substrate; and